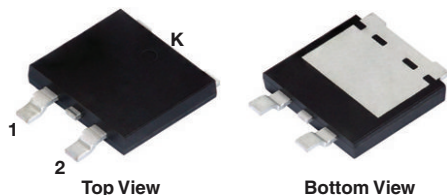


# Dual Low-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.29\text{ V}$  at  $I_F = 5.0\text{ A}$

## eSMP® Series SMPD (TO-263AC)



## LINKS TO ADDITIONAL RESOURCES



## FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:  
- Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	60 V
$I_{FSM}$	320 A
$V_F$ at $I_F = 30\text{ A}$ ( $T_J = 125\text{ °C}$ )	0.52 V
$T_J$ max.	150 °C
Package	SMPD (TO-263AC)
Circuit configuration	Common cathode

## MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

## MAXIMUM RATINGS ( $T_A = 25\text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V60DL63C	UNIT
Device marking code		V60DL63C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	60	V
Maximum average forward rectified current per device (fig. 1) per diode	$I_{F(AV)}^{(1)}$	60 30	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load per diode	$I_{FSM}$	320	A
Operating junction temperature range	$T_J^{(2)}$	-40 to +150	°C
Storage temperature range	$T_{STG}$	-55 to +150	

### Notes

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 5 A	T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.41	-	V
	I <sub>F</sub> = 15 A			0.48	-	
	I <sub>F</sub> = 30 A			0.56	0.63	
	I <sub>F</sub> = 5 A	T <sub>J</sub> = 125 °C		0.29	-	
	I <sub>F</sub> = 15 A			0.40	-	
	I <sub>F</sub> = 30 A			0.52	0.58	
Reverse current at rated V <sub>R</sub> per diode	V <sub>R</sub> = 60 V	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	0.7	mA
		T <sub>J</sub> = 125 °C		20	50	
Typical junction capacitance per diode	4.0 V, 1 MHz		C <sub>J</sub>	4700	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V60DL63C	UNIT
Typical thermal resistance per device	$R_{\theta JC}^{(1)}$	0.8	$^{\circ}\text{C/W}$
	$R_{\theta JA}^{(2)(3)}$	50	

**Notes**

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-ambient

(3) Free air, without heatsink

**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V60DL63C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
V60DL63CHM3/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

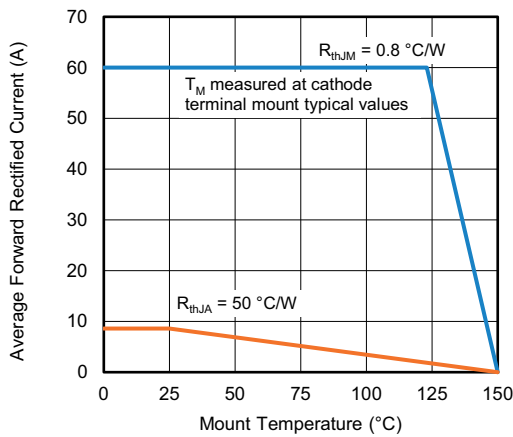
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

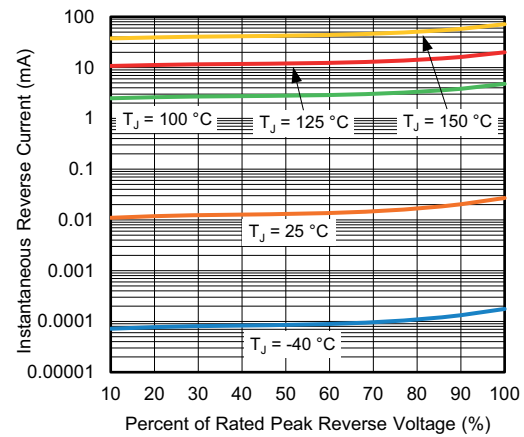


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

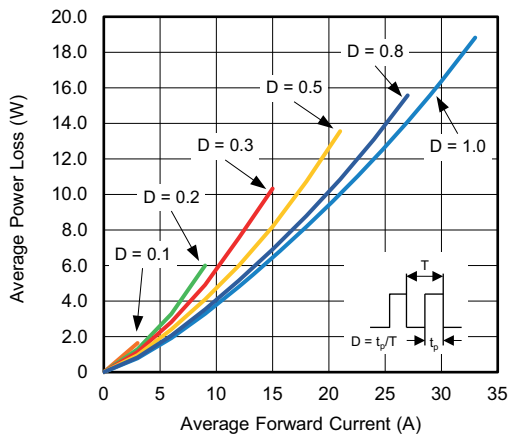


Fig. 2 - Average Power Loss Characteristics Per Diode

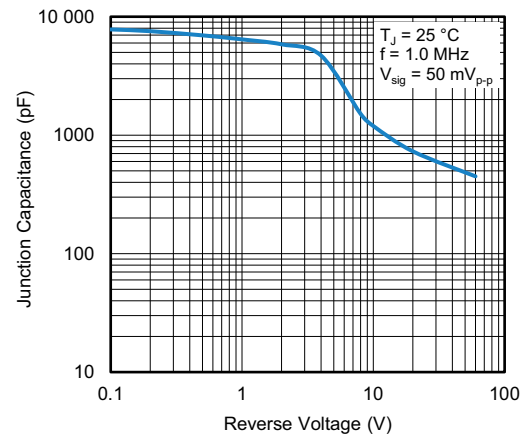


Fig. 5 - Typical Junction Capacitance Per Diode

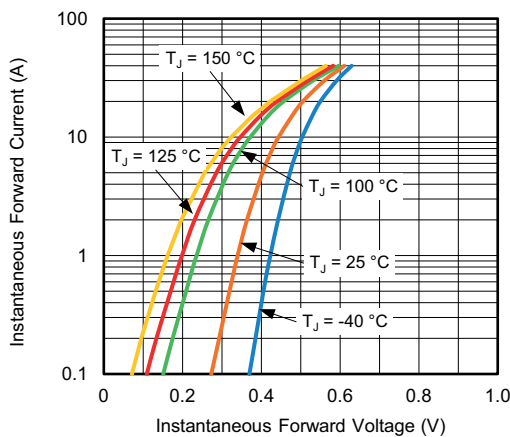


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

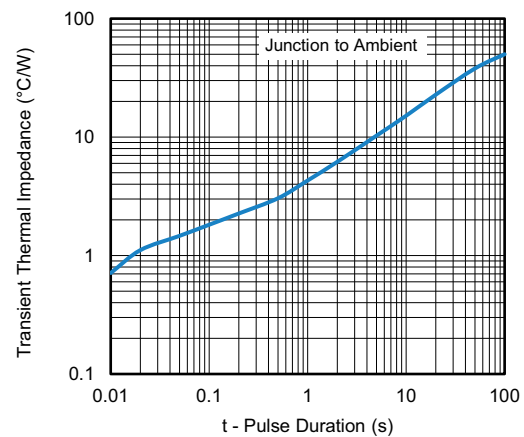


Fig. 6 - Typical Transient Thermal Impedance

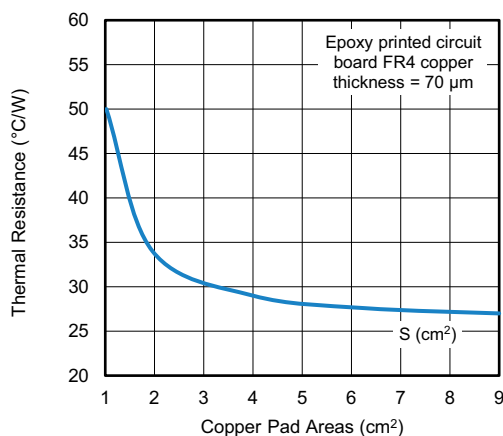
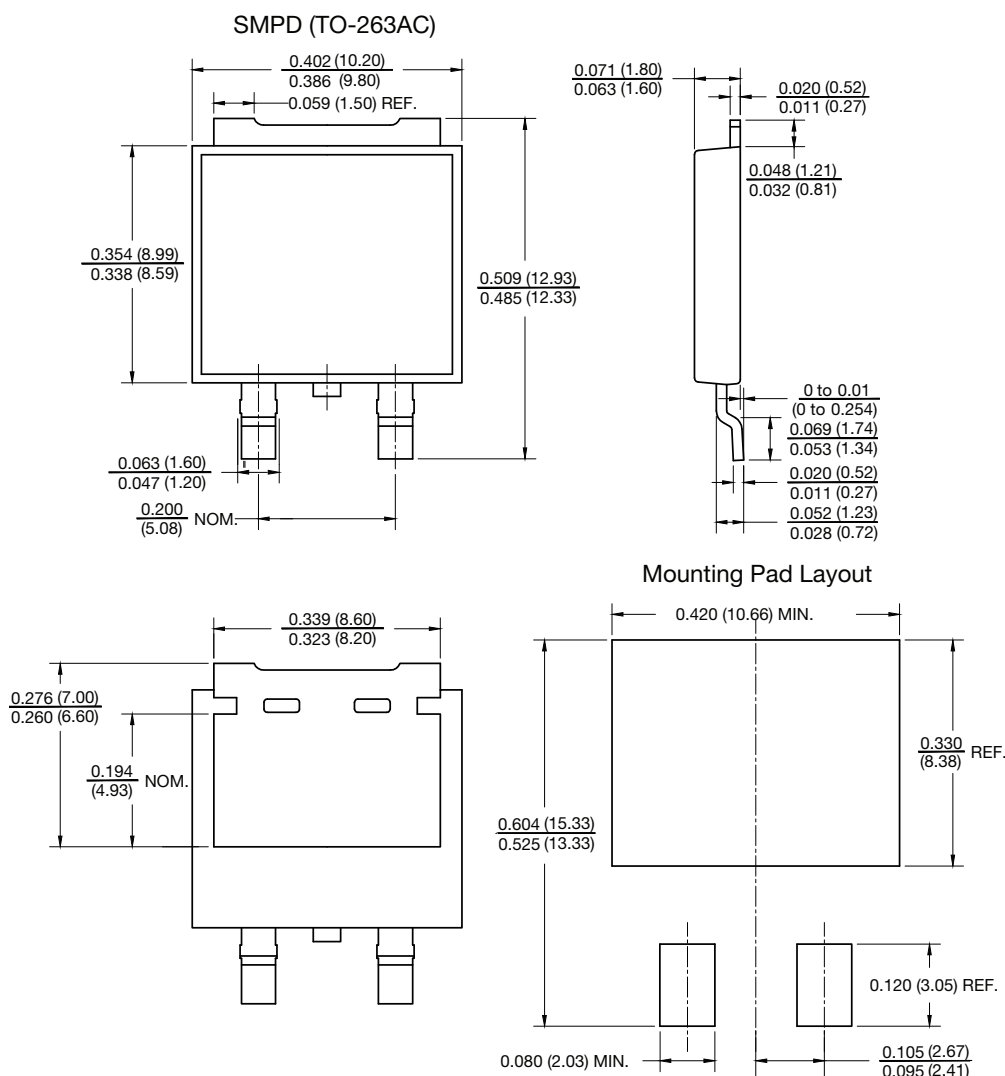


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)




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